TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2601

DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 0.75 Ω (typ.)

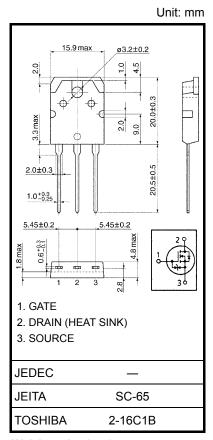
• High forward transfer admittance $: |Y_{fs}| = 7.0 \text{ S (typ.)}$

• Low leakage current $: I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 500 \text{ V)}$

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

| Characteris | stics | Symbol | Rating | Unit | |
|--|------------------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 500 | V | |
| Drain-gate voltage (Ro | _{SS} = 20 kΩ) | V_{DGR} | 500 | V | |
| Gate-source voltage | | V_{GSS} | ±30 | V | |
| Drain current | DC (Note 1) | I _D | 10 | Α | |
| Diam current | Pulse (Note 1) | I _{DP} | 40 | Α | |
| Drain power dissipation | n (Tc = 25°C) | P_{D} | 125 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 270 | mJ | |
| Avalanche current | | I _{AR} | 10 | Α | |
| Repetitive avalanche e | nergy (Note 3) | E _{AR} | 12.5 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature ra | ange | T _{stg} | -55~150 | °C | |



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|-----|------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 1.0 | °C/W |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 50 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 4.59 mH, R_G = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



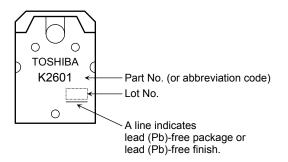
Electrical Characteristics (Ta = 25°C)

| Charac | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|-----------------|----------------------|--|-----|------|-----|------|
| Gate leakage cu | ırrent | I _{GSS} | V _{GS} = ±25 V, V _{DS} = 0 V | _ | _ | ±10 | μΑ |
| Gate-source bre | eakdown voltage | V (BR) GSS | $I_G = \pm 10 \mu A, V_{DS} = 0 V$ | ±30 | _ | _ | V |
| Drain cut-off cu | rrent | I _{DSS} | V _{DS} = 500 V, V _{GS} = 0 V | _ | _ | 100 | μA |
| Drain-source br | eakdown voltage | I (BR) DSS | I _D = 10 mA, V _{GS} = 0 V | 500 | _ | _ | V |
| Gate threshold v | oltage/ | V_{th} | V _{DS} = 10 V, I _D = 1 mA | 2.0 | _ | 4.0 | V |
| Drain-source O | N resistance | R _{DS} (ON) | V _{GS} = 10 V, I _D = 5 A, | _ | 0.75 | 1.0 | Ω |
| Forward transfer | r admittance | Y _{fs} | V _{DS} = 10 V, I _D = 5 A | 3.5 | 7.0 | _ | S |
| Input capacitano | e | C _{iss} | | _ | 1200 | _ | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 200 | _ | pF |
| Output capacitance | | Coss | | _ | 550 | _ | |
| Switching time | Rise time | t _r | $V_{GS} \stackrel{10 \text{ V}}{\circ} V \stackrel{\text{I}_{D}}{\longrightarrow} \stackrel{5 \text{ A}}{\circ} V_{OUT}$ $R_{L} = 60 \Omega$ $V_{DD} \doteq 300 \text{ V}$ | _ | 30 | _ | |
| | Turn-on time | t _{on} | | ı | 50 | | ns |
| | Fall time | t _f | | ı | 45 | | 113 |
| | Turn-off time | t _{off} | Duty $\leq 1\%$, $t_{\rm w} = 10 \mu \rm s$ | - | 180 | _ | |
| Total gate charge (gate-source plus gate-drain) | | Qg | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ | | 30 | | nC |
| Gate-source charge | | Q_{gs} | | _ | 15 | _ | |
| Gate-drain ("miller") Charge | | Q_{gd} | | | 15 | _ | |

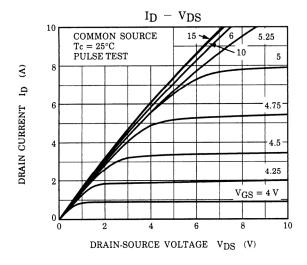
Source-Drain Ratings and Characteristics (Ta = 25°C)

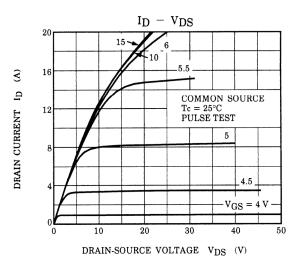
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | _ | _ | 10 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | - | _ | _ | 40 | А |
| Forward voltage (diode) | V _{DSF} | I _{DR} = 10 A, V _{GS} = 0 V | _ | _ | -1.7 | V |
| Reverse recovery time | t _{rr} | I _{DR} = 10 A, V _{GS} = 0 V | 1 | 1200 | | ns |
| Reverse recovery charge | Qrr | dI _{DR} / dt = 100 A / μs | _ | 10 | _ | μC |

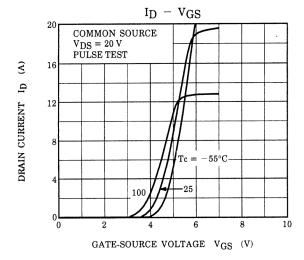
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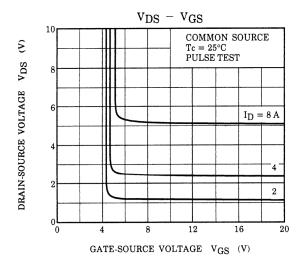


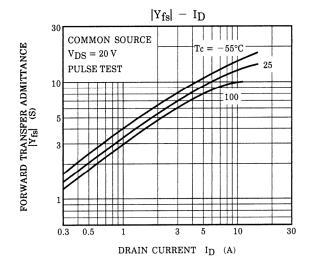
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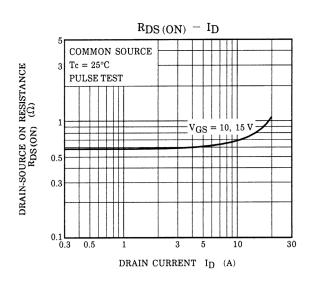


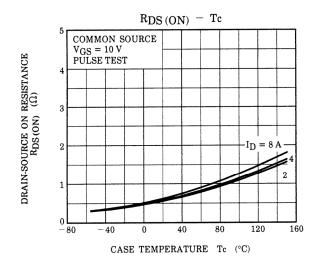


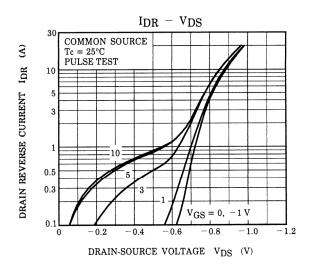


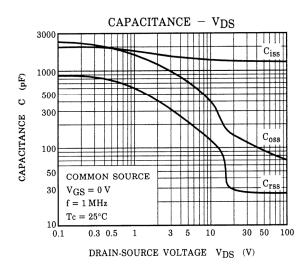


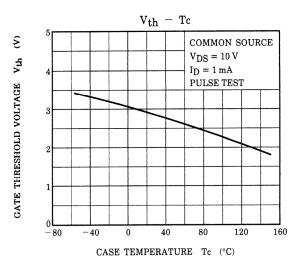


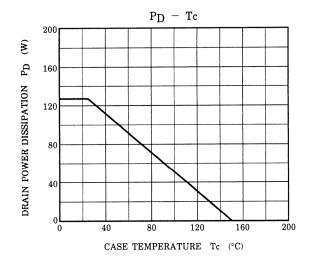


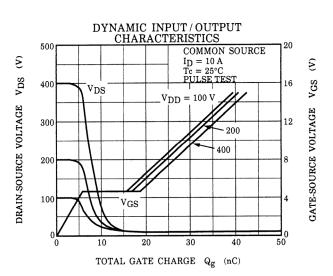


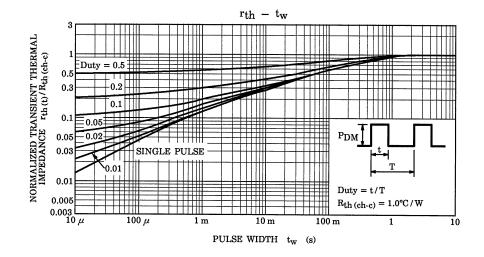


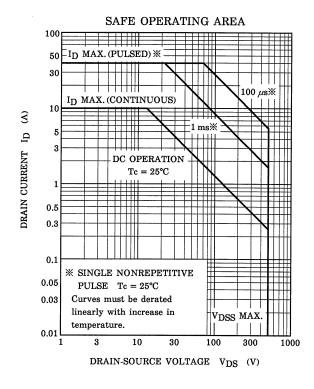


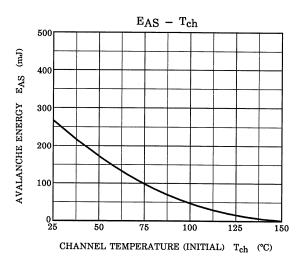


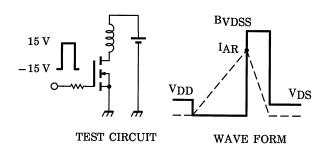












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 4.59~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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